

Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1. (Canceled)
2. (Currently Amended) The ink composition according to ~~Claim 1~~Claim 5, wherein the azole-based silane coupling agent is ~~imidazolesilane~~an imidazole-silane.
3. (Canceled)
4. (Canceled)
5. (New) In an ink composition used in an inkjet process for drawing a wiring pattern on a substrate, the improvement comprising said ink composition containing from 0.01 to 100 g/L of an azole-based silane coupling agent as a coupling agent for an electroless plating activator.
6. (New) The ink composition of Claim 5, wherein the electroless plating activator is contained therein.
7. (New) The ink composition of Claim 6, wherein the electroless plating activator is present at a concentration of from 0.01 to 100 g/L.
8. (New) The ink composition of Claim 6, wherein a viscosity adjuster and a surface-tension adjuster are also contained therein.
9. (New) The ink composition of Claim 6, wherein the electroless plating activator is a noble metal compound.

10. (New) The ink composition of Claim 9, wherein the noble metal compound is palladium chloride.

11. (New) The ink composition of Claim 10, wherein the azole-based silane coupling agent is a reaction product of imidazole and γ -glycidoxypyrtrimethoxysilane.

12. (New) In a method of drawing a wiring pattern on a substrate by applying an ink composition by an inkjet process, the improvement comprising the ink composition is the ink composition of Claim 5.

13. (New) In a method of coating a wiring pattern on a substrate with a metal comprising the steps of drawing a wiring pattern on a substrate by applying an ink composition by an inkjet process, immersing the substrate in an activator solution and electrolessly plating the substrate with the metal, the improvement comprising the ink composition is the ink composition of Claim 5.